LB A67C

SIDELED®

Applications

- Cluster, Button Backlighting
- Electronic Equipment
- Interior Illumination (e.g. Ambient Map)

Features:

- Package: white SMT package, colorless clear resin
- Chip technology: InGaN
- Typ. Radiation: 120° (Lambertian emitter)
- Color: λ_{dom} = 470 nm (● blue)
- Corrosion Robustness Class: 3B
- ESD: 2 kV acc. to ANSI/ESDA/JEDEC JS-001 (HBM, Class 2)

Discontinued

Ordering Information

Type	Luminous Intensity [1] I_F = 20 mA I_v	Ordering Code
LB A67C-P2S1-35-1	56 ... 224 mcd	Q65112A2768

Discontinued

Maximum Ratings

Parameter	Symbol		Values
Operating Temperature	T_{op}	min. max.	-40 °C 100 °C
Storage Temperature	T_{stg}	min. max.	-40 °C 100 °C
Junction Temperature	T_j	max.	110 °C
Forward current T_S = 25 °C	I_F	max.	20 mA
Surge Current t ≤ 10 µs; D = 0.005 ; T_S = 25 °C	I_{FS}	max.	300 mA
Reverse voltage [2)] T_S = 25 °C	V_R	max.	5 V
ESD withstand voltage acc. to ANSI/ESDA/JEDEC JS-001 (HBM, Class 2)	V_{ESD}		2 kV

Discontinued

Characteristics

I_F = 20 mA; T_S = 25 °C

Parameter	Symbol		Values
Peak Wavelength	λ_{peak}	typ.	465 nm
Dominant Wavelength [3] I_F = 20 mA	λ_{dom}	min. typ. max.	464 nm 470 nm 476 nm
Spectral Bandwidth at 50% $I_{rel,max}$	$\Delta\lambda$	typ.	25 nm
Viewing angle at 50% I_V	2φ	typ.	120 °
Forward Voltage [4] I_F = 20 mA	V_F	min. typ. max.	3.00 V 3.20 V 3.90 V
Reverse current [2] V_R = 5 V	I_R	typ. max.	0.01 µA 10 µA
Temperature Coefficient of Peak Wavelength -10°C ≤ T ≤ 100°C	$TC_{\lambda peak}$	typ.	0.04 nm / K
Real thermal resistance junction/ambient [5)6)]	$R_{thJA\ real}$	max.	480 K / W
Real thermal resistance junction/solderpoint [5)]	$R_{thJS\ real}$	max.	250 K / W

Discontinued

Brightness Groups

Group	Luminous Intensity [1] I_F = 20 mA min. I_v	Luminous Intensity. [1] I_F = 20 mA max. I_v	Luminous Flux [7] I_F = 20 mA typ. Φ_V
P2	56 mcd	71 mcd	230 mlm
Q1	71 mcd	90 mcd	290 mlm
Q2	90 mcd	112 mcd	360 mlm
R1	112 mcd	140 mcd	450 mlm
R2	140 mcd	180 mcd	580 mlm
S1	180 mcd	224 mcd	730 mlm

Forward Voltage Groups

Group	Forward Voltage [4] I_F = 20 mA min. V_F	Forward Voltage [4] I_F = 20 mA max. V_F
66	3.00 V	3.30 V
C6	3.30 V	3.60 V
J6	3.60 V	3.90 V

Wavelength Groups

Group	Dominant Wavelength [3] I_F = 20 mA min. λ_{dom}	Dominant Wavelength [3] I_F = 20 mA max. λ_{dom}
3	464 nm	468 nm
4	468 nm	472 nm
5	472 nm	476 nm

Discontinued

Group Name on Label

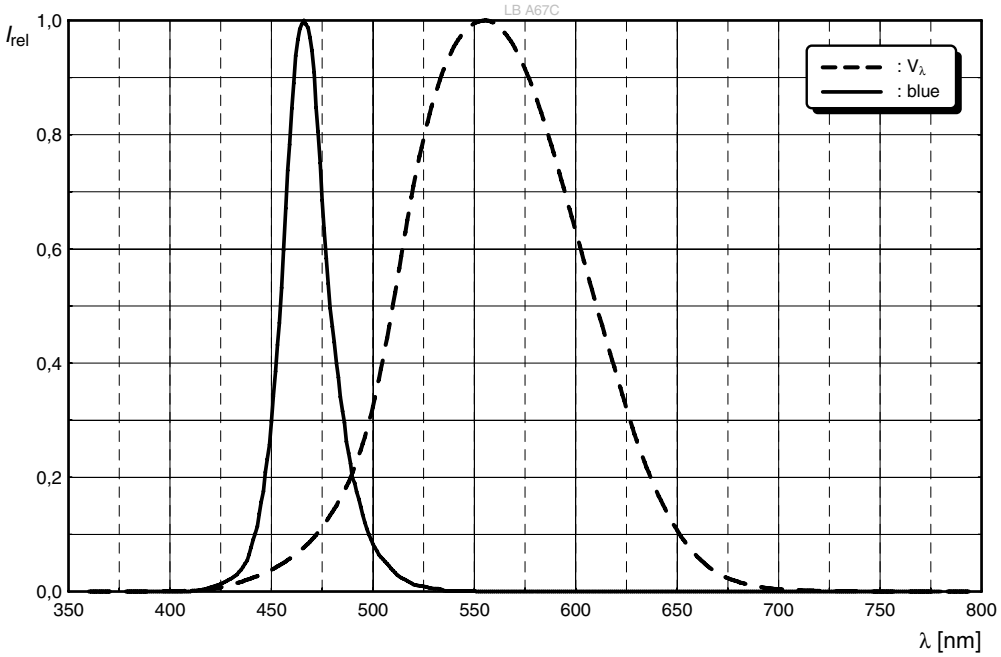
Example: P2-3-66

Brightness	Wavelength	Forward Voltage
P2	3	66

Discontinued

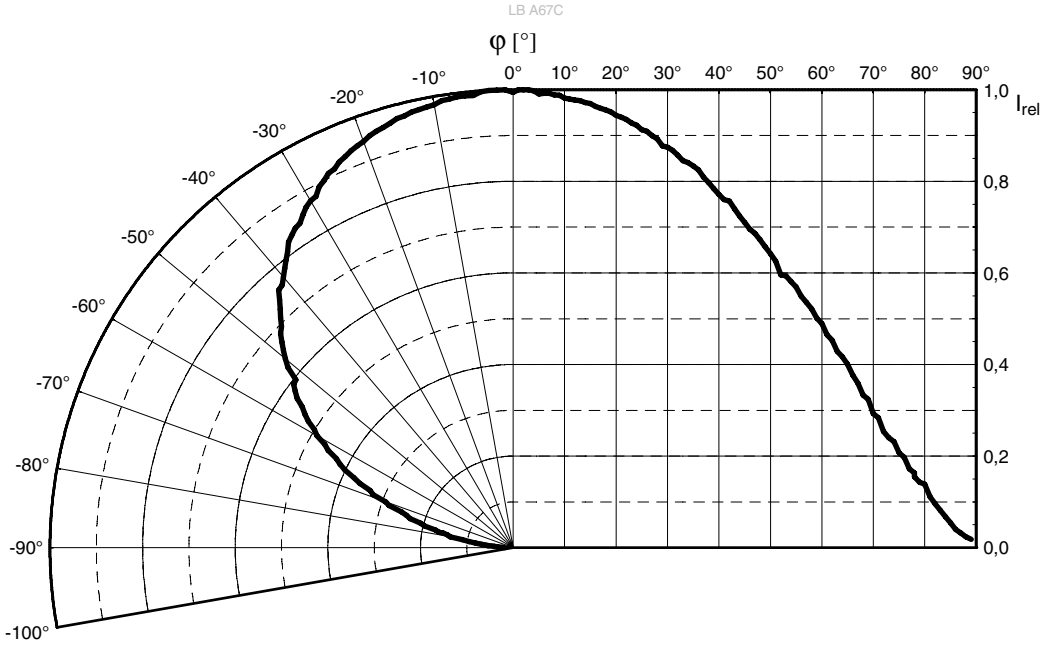
Relative Spectral Emission [7)]

$I_{rel} = f(\lambda)$; $I_F = 20$ mA; $T_S = 25$ °C



Radiation Characteristics [7)]

$I_{rel} = f(\phi)$; $T_S = 25$ °C



Discontinued

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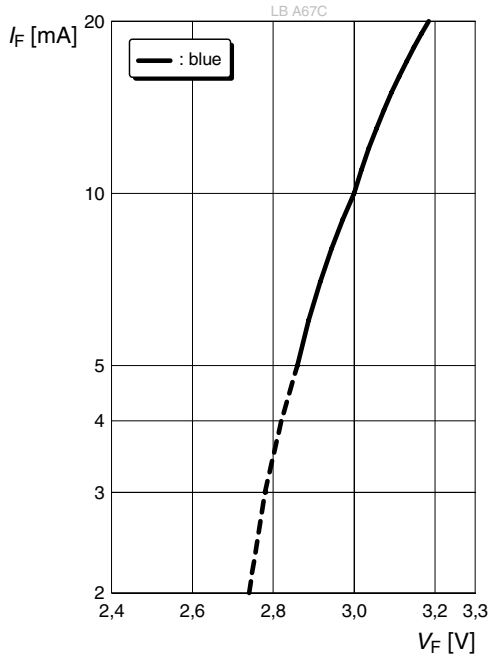
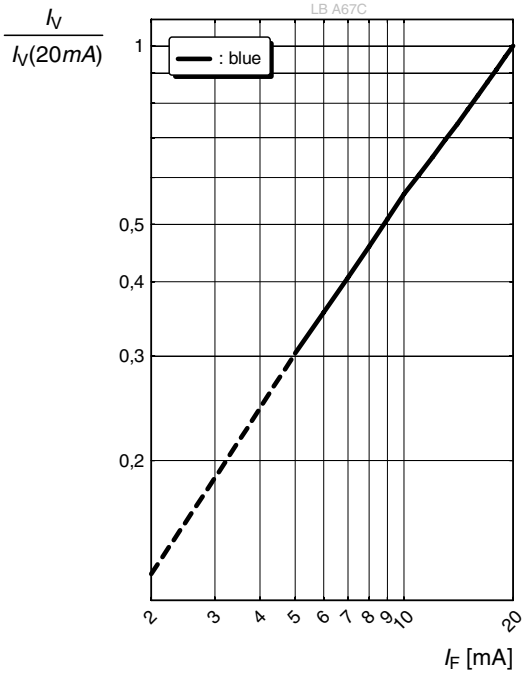
Forward current [7), 8)]

$I_F = f(V_F)$; T_S = 25 °C



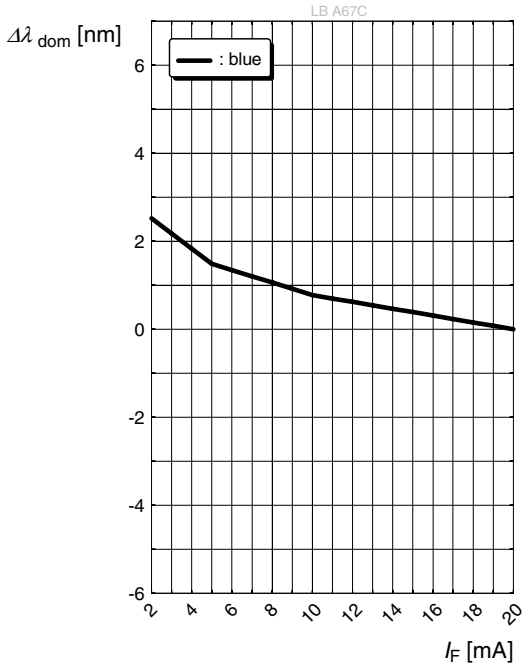
Relative Luminous Intensity [7), 8)]

$I_v/I_v(20\ mA) = f(I_F)$; T_S = 25 °C



Dominant Wavelength [7)]

$\Delta\lambda_{dom} = f(I_F)$; T_S = 25 °C



Discontinued

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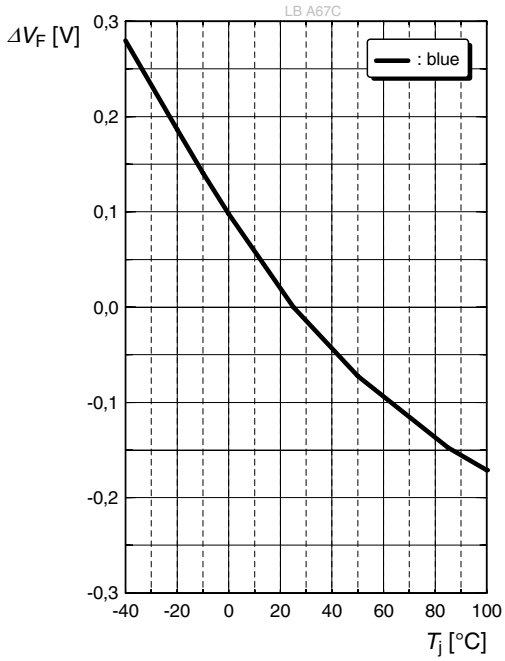
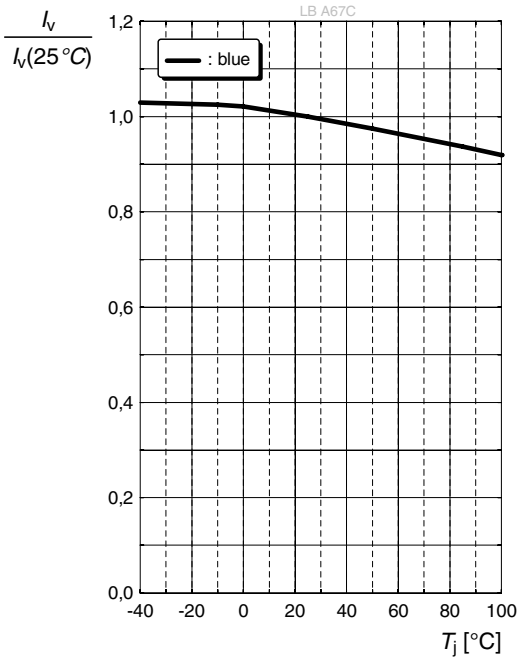
Forward Voltage [7)]

$\Delta V_F = V_F - V_F(25\ °C) = f(T_j);\ I_F = 20\ mA$



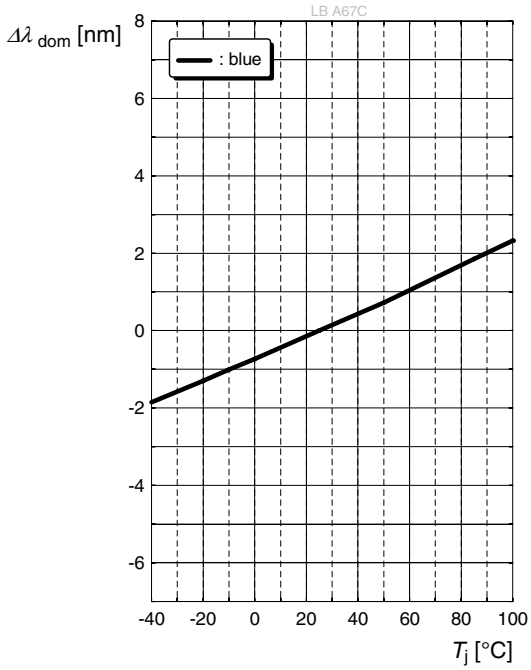
Relative Luminous Intensity [7)]

$I_v/I_v(25\ °C) = f(T_j);\ I_F = 20\ mA$



Dominant Wavelength [7)]

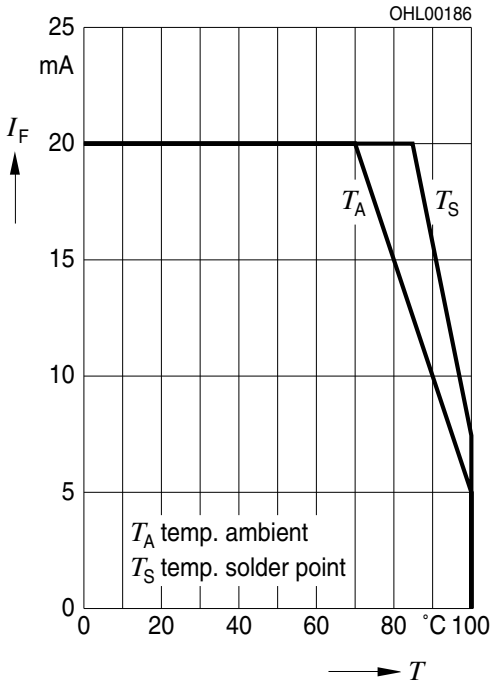
$\Delta\lambda_{dom} = \lambda_{dom} - \lambda_{dom}(25\ °C) = f(T_j);\ I_F = 20\ mA$



Discontinued

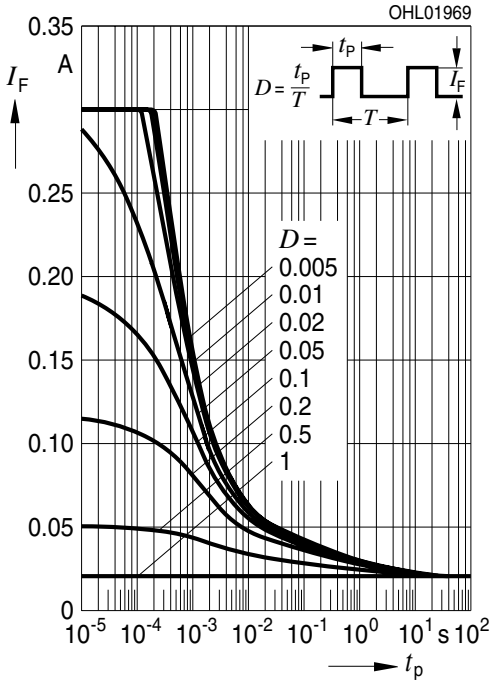
Max. Permissible Forward Current

$I_F = f(T)$



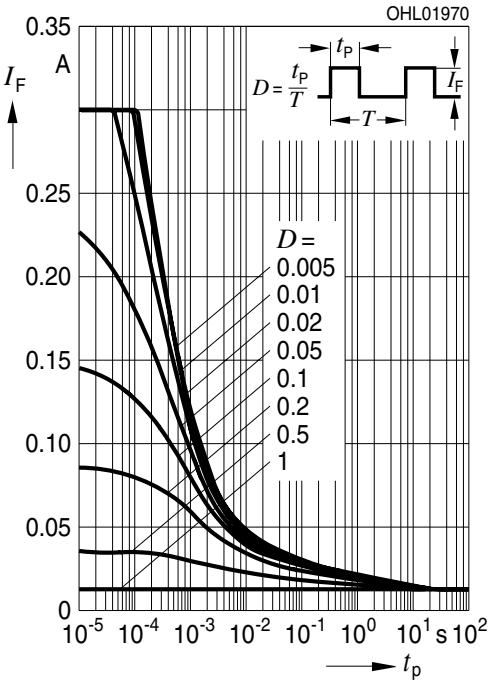
Permissible Pulse Handling Capability

$I_F = f(t_p)$; D: Duty cycle; T_A = 25 °C



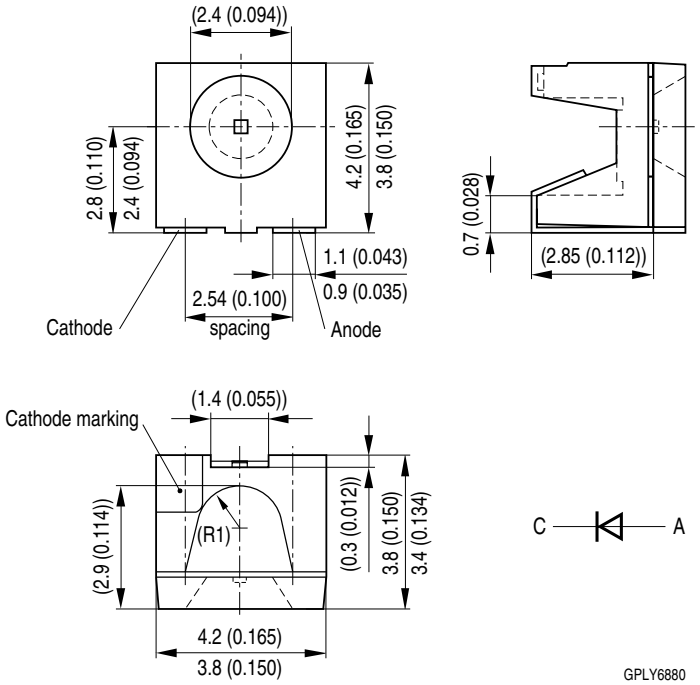
Permissible Pulse Handling Capability

$I_F = f(t_p)$; D: Duty cycle; T_A = 85 °C



Discontinued

Dimensional Drawing [9)]



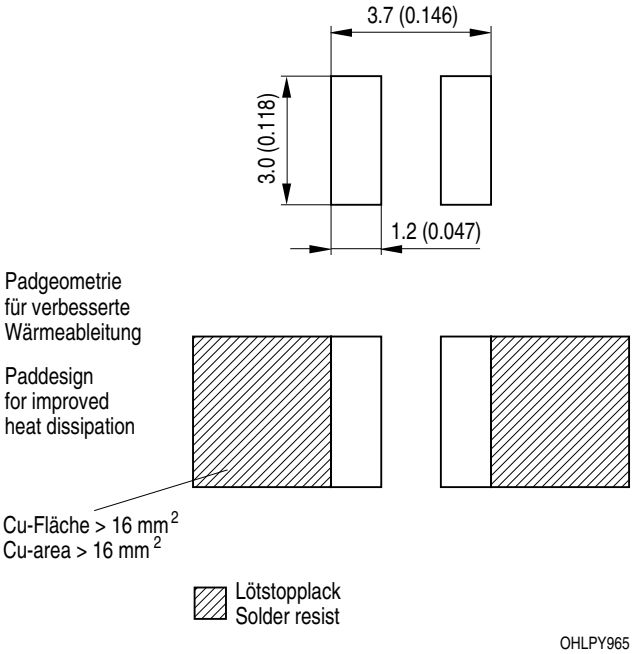
Further Information

Approximate Weight: 67.0 mg

Corrosion test: Class: 3B
Test condition: 40°C / 90 % RH / 15 ppm H_2S / 14 days (stricter than IEC 60068-2-43)

Discontinued

Recommended Solder Pad [9)]

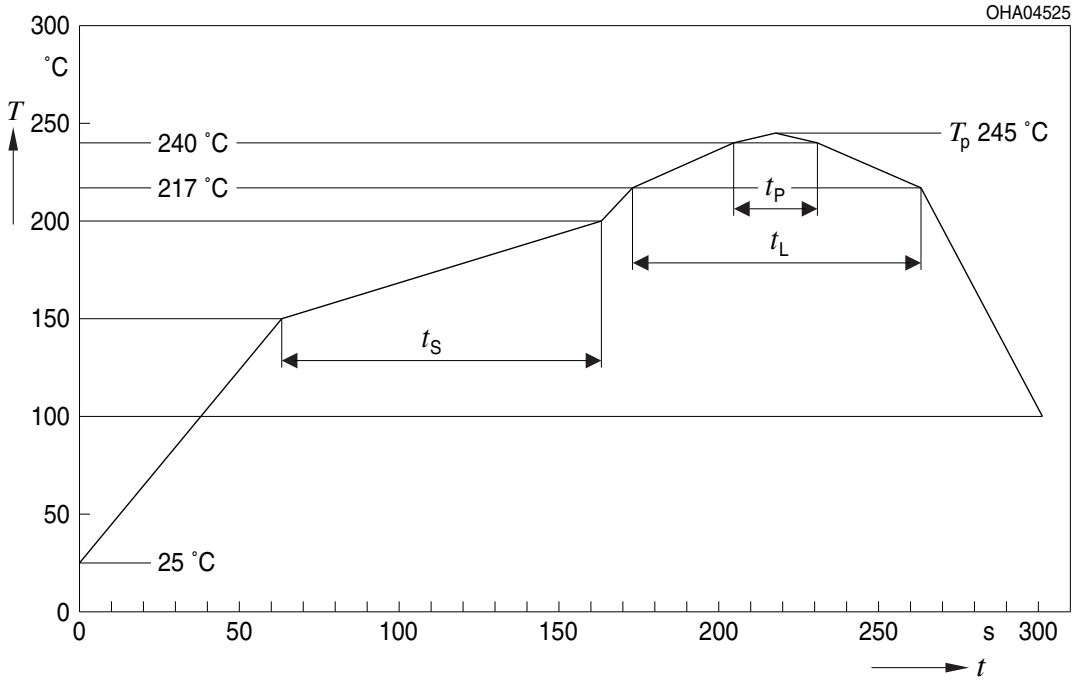


For superior solder joint connectivity results we recommend soldering under standard nitrogen atmosphere. Package not suitable for ultra sonic cleaning.

Discontinued

Reflow Soldering Profile

Product complies to MSL Level 2 acc. to JEDEC J-STD-020E

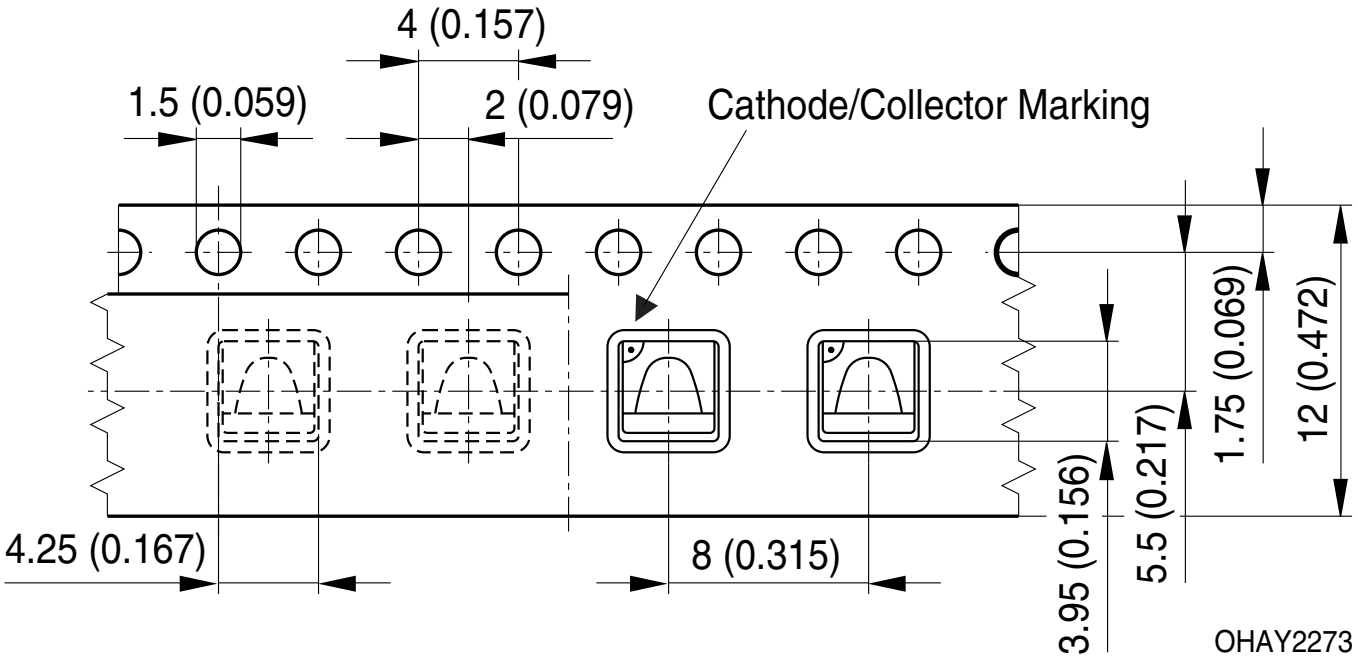


Profile Feature	Symbol	Pb-Free (SnAgCu) Assembly			Unit
		Minimum	Recommendation	Maximum	
Ramp-up rate to preheat*) 25 °C to 150 °C			2	3	K/s
Time t_S T_{Smin} to T_{Smax}	t_S	60	100	120	s
Ramp-up rate to peak*) T_{Smax} to T_P			2	3	K/s
Liquidus temperature	T_L		217		°C
Time above liquidus temperature	t_L		80	100	s
Peak temperature	T_P		245	250	°C
Time within 5 °C of the specified peak temperature T_P - 5 K	t_P	10	20	30	s
Ramp-down rate* T_P to 100 °C			3	4	K/s
Time 25 °C to T_P				480	s

All temperatures refer to the center of the package, measured on the top of the component
* slope calculation DT/Dt: Dt max. 5 s; fulfillment for the whole T-range

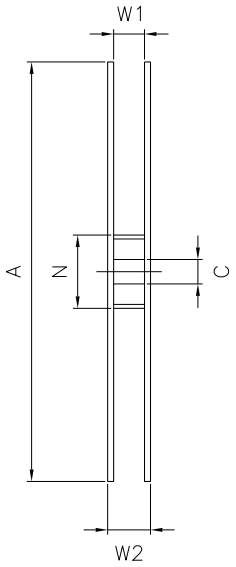
Discontinued

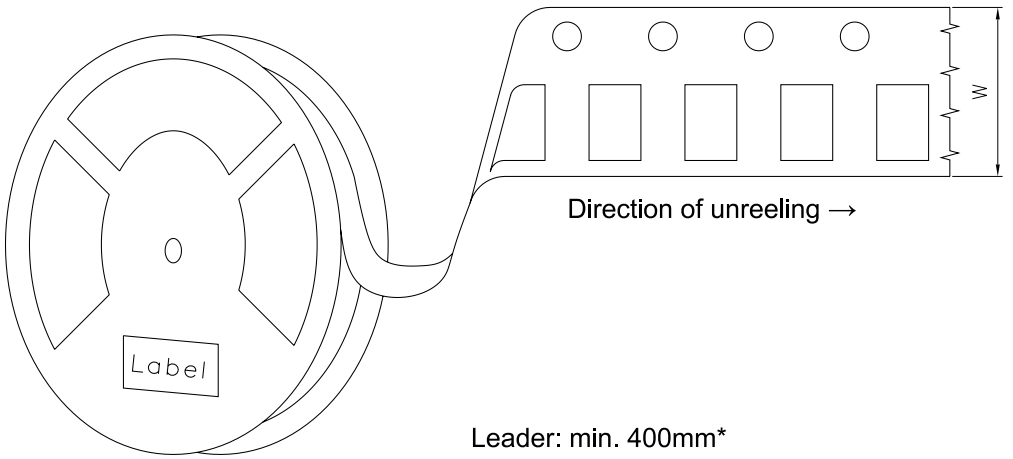
Taping [9)]



Discontinued

Tape and Reel [10)]





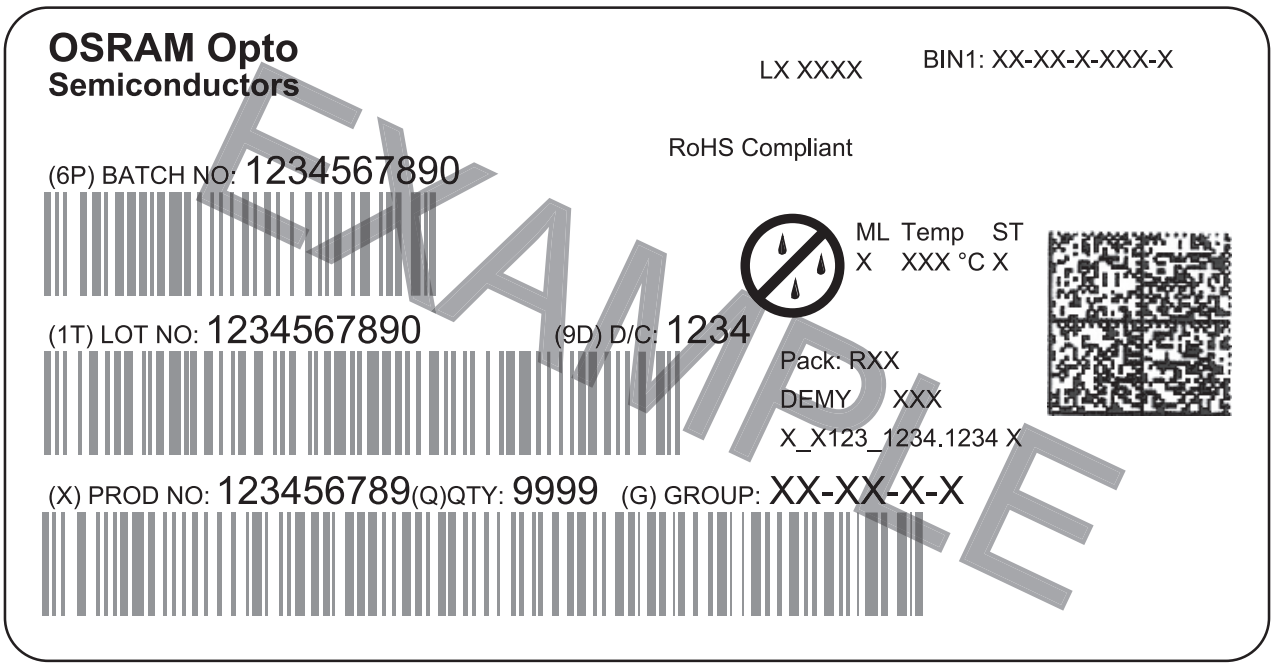
Leader: min. 400mm*
Trailer: min. 160mm*
*)Dimensions acc. to IEC 60286-3; EIA 481-E

Reel Dimensions

A	W	N_{min}	W_1	$W_{2\,max}$	Pieces per PU
330 mm	12 + 0.3 / - 0.1 mm	60 mm	12.4 + 2 mm	18.4 mm	2000

Discontinued

Barcode-Product-Label (BPL)



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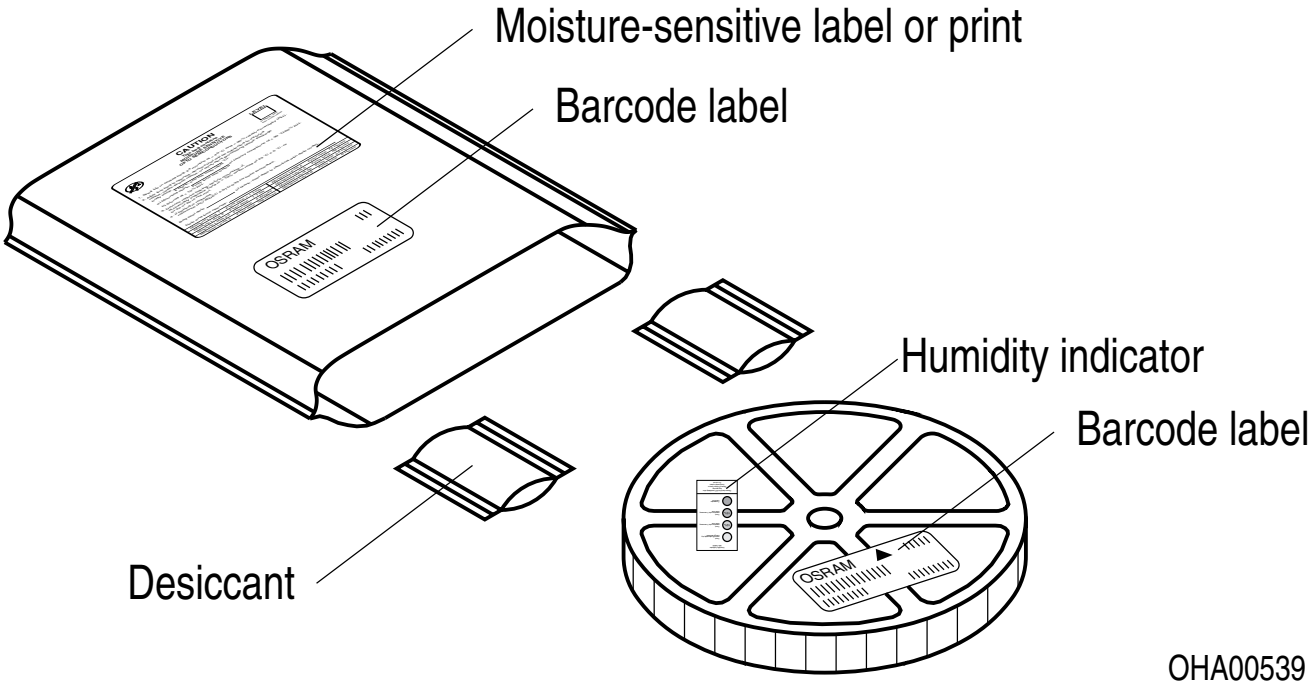
Dry Packing Process and Materials [9)]



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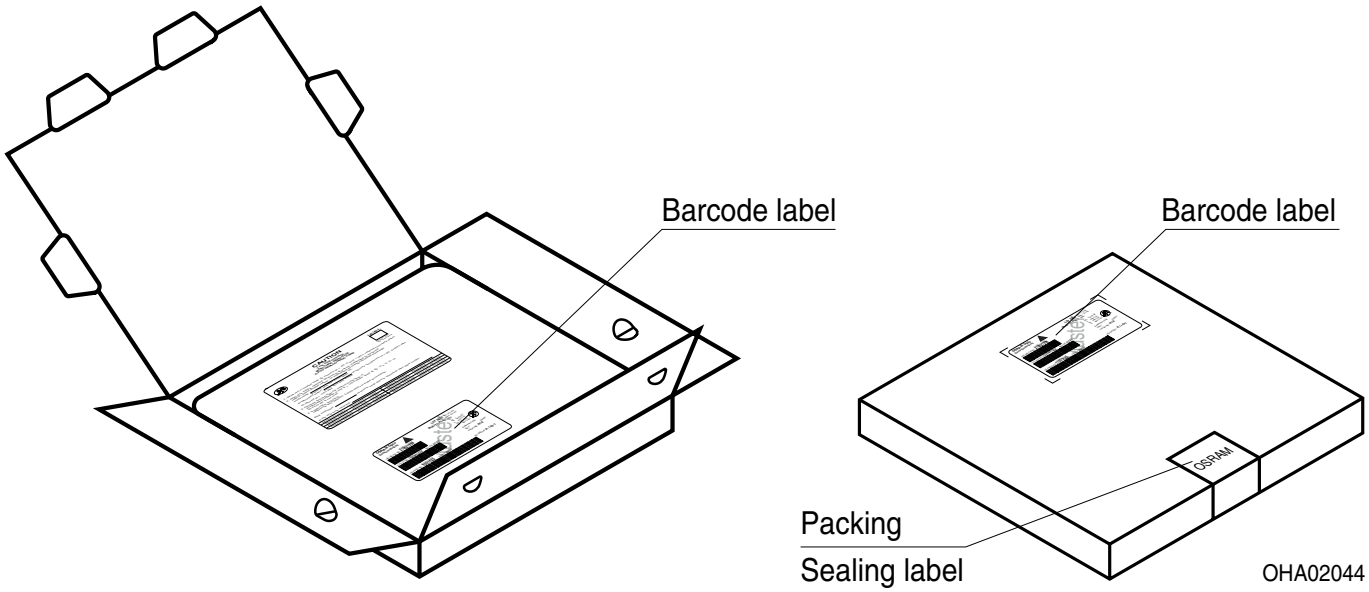
Moisture-sensitive product is packed in a dry bag containing desiccant and a humidity card according JEDEC-STD-033.

Discontinued

Schematic Transportation Box [9)]

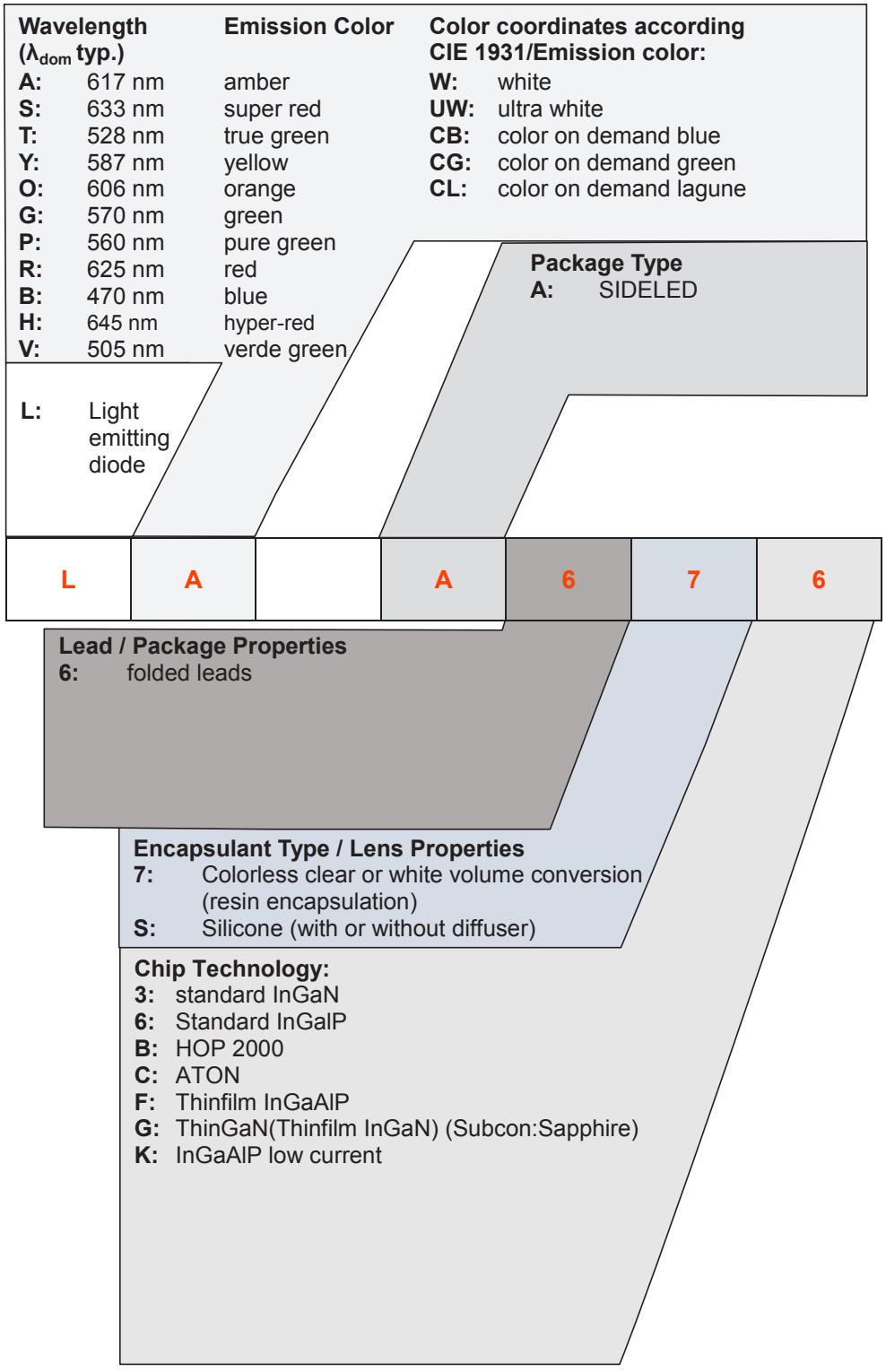


Dimensions of Transportation Box

Width	Length	Height
349 ± 5 mm	349 ± 5 mm	33 ± 5 mm

Discontinued

Type Designation System



Discontinued

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Notes

The evaluation of eye safety occurs according to the standard IEC 62471:2006 (photo biological safety of lamps and lamp systems). Within the risk grouping system of this IEC standard, the device specified in this data sheet falls into the class **exempt group (exposure time 10000 s)**. Under real circumstances (for exposure time, conditions of the eye pupils, observation distance), it is assumed that no endangerment to the eye exists from these devices. As a matter of principle, however, it should be mentioned that intense light sources have a high secondary exposure potential due to their blinding effect. When looking at bright light sources (e.g. headlights), temporary reduction in visual acuity and afterimages can occur, leading to irritation, annoyance, visual impairment, and even accidents, depending on the situation.

Subcomponents of this device contain, in addition to other substances, metal filled materials including silver. Metal filled materials can be affected by environments that contain traces of aggressive substances. Therefore, we recommend that customers minimize device exposure to aggressive substances during storage, production, and use. Devices that showed visible discoloration when tested using the described tests above did show no performance deviations within failure limits during the stated test duration. Respective failure limits are described in the IEC60810.

For further application related information please visit www.osram-os.com/appnotes

Discontinued

Disclaimer

Attention please!
The information describes the type of component and shall not be considered as assured characteristics.
Terms of delivery and rights to change design reserved. Due to technical requirements components may contain dangerous substances.
For information on the types in question please contact our Sales Organization.
If printed or downloaded, please find the latest version on the OSRAM OS website.

Packing
Please use the recycling operators known to you. We can also help you – get in touch with your nearest sales office. By agreement we will take packing material back, if it is sorted. You must bear the costs of transport. For packing material that is returned to us unsorted or which we are not obliged to accept, we shall have to invoice you for any costs incurred.

Product and functional safety devices/applications or medical devices/applications
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OSRAM OS products are not qualified at module and system level for such application.

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Discontinued

Glossary

1) **Brightness:** Brightness values are measured during a current pulse of typically 25 ms, with an internal reproducibility of ±8 % and an expanded uncertainty of ±11 % (acc. to GUM with a coverage factor of k = 3).

2) **Reverse Operation:** Reverse Operation of 10 hours is permissible in total. Continuous reverse operation is not allowed.

3) **Wavelength:** The wavelength is measured at a current pulse of typically 25 ms, with an internal reproducibility of ±0.5 nm and an expanded uncertainty of ±1 nm (acc. to GUM with a coverage factor of k = 3).

4) **Forward Voltage:** The forward voltage is measured during a current pulse of typically 8 ms, with an internal reproducibility of ±0.05 V and an expanded uncertainty of ±0.1 V (acc. to GUM with a coverage factor of k = 3).

5) **Thermal Resistance:** Rth max is based on statistic values (6σ).

6) **Thermal Resistance:** RthJA results from mounting on PC board FR 4 (pad size 16 mm² per pad)

7) **Typical Values:** Due to the special conditions of the manufacturing processes of semiconductor devices, the typical data or calculated correlations of technical parameters can only reflect statistical figures. These do not necessarily correspond to the actual parameters of each single product, which could differ from the typical data and calculated correlations or the typical characteristic line. If requested, e.g. because of technical improvements, these typ. data will be changed without any further notice.

8) **Characteristic curve:** In the range where the line of the graph is broken, you must expect higher differences between single devices within one packing unit.

9) **Tolerance of Measure:** Unless otherwise noted in drawing, tolerances are specified with ±0.1 and dimensions are specified in mm.

10) **Tape and Reel:** All dimensions and tolerances are specified acc. IEC 60286-3 and specified in mm.

Discontinued

Revision History

Version	Date	Change
1.8	2019-07-15	Discontinued

Discontinued

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EU RoHS and China RoHS compliant product

此产品符合欧盟 RoHS 指令的要求；
按照中国的相关法规和标准，不含有毒有害物质或元素。

Discontinued

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Общество с ограниченной ответственностью «МосЧип» ИНН 7719860671 / КПП 771901001
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Данный компонент на территории Российской Федерации

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http://moschip.ru/get-element

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